



December 17, 2003

To: Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
 28 Davis Avenue
 Poughkeepsie, N.Y. 12603

Subject:		Serial No. 10/682,054 10/09/03
	Kim Hwee Tan et al.	
	PILLAR STRUCTURES	

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
 In An Application.

The following Patents and/or Publications are submitted to
 comply with the duty of disclosure under CFR 1.97-1.99 and
 37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
 deposited with the United States Postal Service as first class
 mail in an envelope addressed to: Commissioner for Patents,
 P.O. Box 1450, Alexandria, VA 22313-1450, on December 19, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

S. B. A. 12/19/03

"Advanced Connections," Spring 2002, Advanced Interconnect Technologies, issue describes, inter alia, a pillar bumping interconnect technology that uses perimeter or array flip-chip pads to connect an integrated circuit (IC) to a copper lead frame.

U.S. Patent 6,550,666 to Chew et al., "Method for Forming a Flip Chip on Leadframe Semiconductor Package," discloses a method for forming a flip chip on leadframe semiconductor package.

U.S. Patent 5,448,114 to Kondoh et al., "Semiconductor Flipchip Packaging Having a Perimeter Wall," discloses a semiconductor flip chip packaging having a perimeter wall.

U.S. Patent 6,297,551 to Dudderar et al., "Integrated Circuit Packages with Improved EMI Characteristics," discloses integrated circuit packages with improved EMI characteristics.

U.S. Patent 4,430,690 to Chance et al., "Low Inductance MLC Capacitor with Metal Impregnation and Solder Bar Contact," discloses a low inductance capacitor with metal impregnation and solder bar contact.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761



Form PTO-1449

1 P E INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Doctor's Name (Optional)

APS-03-002

September 1960

10/682,054

Loyalty

Kim Hwee Tan et al.

Chong Party

10/09/03

Group Art Work

U. S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (including Author, Title, Date, Portion of Page, Etc.)

"Advanced Connections," Spring 2002, Advanced
Interconnect Technologies, pp. 1-8.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.